# **Al-Link**

## WF-M620-RSC1

### Features:

> Supported WLAN Standards

IEEE Std. 802.11b IEEE Std. 802.11g

IEEE Std. 802.11n

Chip Solution MTK MT3620AN

> **Size** 22.0mm\*30.0mm\*2.5mm



Product Name	Installation	Data Rate(max)	Band	Antenna Interface	Note
WF-M620-RSC1	SMD	72.2Mbps	2.4 GHz	IPEX/PCB Trace Antenna	DC 3.3V Power Supply

## Sichuan Al-Link Technology Co.,Ltd

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## Feedback of customer's Confirmation

## We accept the specification after Confirmed

Customer name	Customer signature	Confirmation Date

Please feed back this paper and first paper after your signature by the address,thanks!

ADD: Anzhou,Industrial park,Mianyang,Sichuan

Factory: Sichuan Al-Link Technology Co.,Ltd.

Approved	Checked	Designed	Product	WiFi Module
Bai Lang	Ding Shuangpeng	Feng Jie	Model	WF-M620-RSC1
			Date	2019-5-25

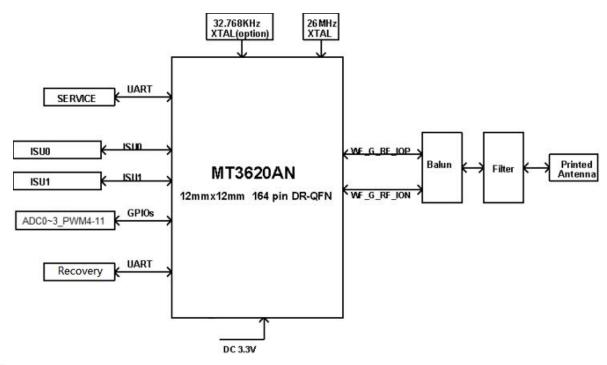
## **Record of Modification**

No	Date of modification	Main content of modification	Reason of modification	Serial number of modification	Confirm
v1.0	20190314	Initial Release			Feng Jie
v1.1	20190415	The product has passed the FCC,CE and MIC certification.Modified the picture of Product.			Feng Jie
V1.2	20190525	Explained the module pin definition in more detail.			Feng Jie

#### 1. Brief Description

The WF-M620-RSC1 IoT module is based on the MediaTek MT3620AN,a highly integrated single chip,tricore WIFI MCU designed to meet the requirements of modern robust internet-connected devices. It leverages the Microsoft Azure Sphere security architecture to provide an unprecedented level of security to connected device manufacturers. For the lifetime of the device the Azure Sphere system provides device authentication and attestation, supports remote over-the-air software updates to maintain security in the face of evolving attacks, and automates error logging and reporting.

#### 1.1 Block Diagram



#### 1.2 WIFI Feature

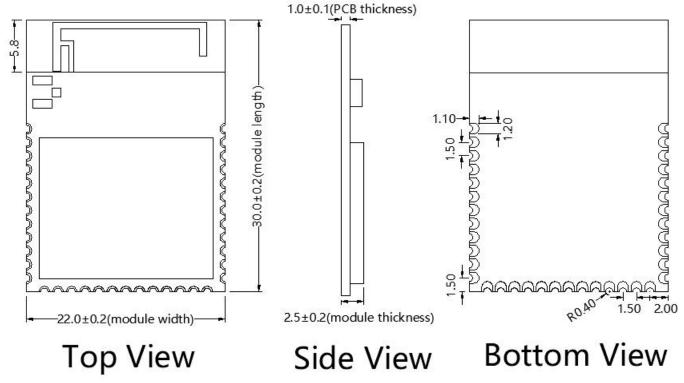
- Single band 2.4GHz ISM
- Supported IEEE 802.11b/g/n

#### 1.3 Hardware Feature

	reature	
No.	Feature	Description
1	Main Chip	MT3620AN
2	RAM Capacity	approximately 5MB(including 256KB in each I/O subsystem and 4MB in the A7 application subsystem)
3	NOR-flash Capacity	16MB on-die and no external flash(The amount of flash that will be accessible to customer software is TBD)
4	Form Factor	37 pins(stamp hole)
5	Size	30 x 22 x 2.5mm±0.2mm
6	Interface	UART×2: ISU0(configured as SPI 0 or UART 0), ISU1(configured as SPI 1 or UART 1 or I2C 1) PWM×8: PWM4~PWM11 ADC×4: ADC0~3 GPIO: 14 GPIO pins with multi-functions
7	Operation Voltage	3.3V+/-0.3
8	Current Consumption	(TBD)
9	Antenna Type	Integral PCB Trace Antenna/Option to fit IPEX connector for external antenna
10	Operating Temperature	-40°C to +85°C
11	Storage Temperature	-45°C to +135°C

### 2. Mechanical Specification(units:mm)

#### 2.1 Mechanical Outline



NOTE:General tolerance ±0.2mm unless otherwise stated

#### 2.2 Pin Definition

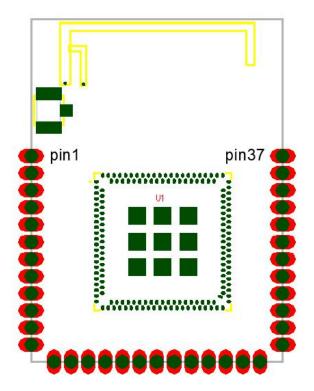


Figure 2.2 Pin assignment

Pin#	Pin name	Type		Des	scription	
1	GPIO41_ADC0/GPIO4_PWM4	ADIO/DIO	GPIO multiplexed with ADC	input o	r PWM output	
2	GPIO42_ADC1/GPIO5_PWM5	ADIO/DIO	GPIO multiplexed with ADC	input o	r PWM output	
3	GPIO43_ADC2/GPIO6_PWM6	ADIO/DIO	GPIO multiplexed with ADC	input o	r PWM output	
4	GPIO44_ADC3/GPIO7_PWM7	ADIO/DIO	GPIO multiplexed with ADC	input o	r PWM output	
5	GPIO26_SCLK0_TXD0/GPIO8 PWM8	DIO/DIO	GPIO multiplexed with ISU0 <sup>[</sup>	<sup>[1]</sup> funct	tions(SPI CLK/UAR	ΓTX) or PWM output
6	GPIO27_MOSI0_RTS0_SCL0/ GPIO9_PWM9	DIO/DIO	GPIO multiplexed with ISU0 functions(SPI MOSI/UART RTS/I2C CLK) or PWM output			
7	GPIO28_MISO0_RXD0_SDA0/ GPIO10_PWM10	DIO/DIO	GPIO multiplexed with ISU0 PWM output	functio	ons(SPI MISO/UART	RX/I2C DATA) or
8	GPIO29_CSA0_CTS0/GPIO11 _PWM11	DIO/DIO	GPIO multiplexed with ISU0	functio	ons(SPI CSA/UART	CTS) or PWM output
9	GPIO30_CSB0	DIO	GPIO multiplexed with ISU0	functio	ons(SPI CSB) or PW	/M output
10	GPIO32_MOSI1_RTS1_SCL1	DIO	GPIO multiplexed with ISU1	functio	ons(SPI MOSI/UART	RTS/I2C CLK)
11	GPIO34_CSA1_CTS1	DIO	GPIO multiplexed with ISU1	functio	ons(SPI CSA/UART	CTS)
12	GND	G	Ground			
13	GND	G	Ground			
14	GPIO31_SCLK1_TXD1	DIO	GPIO multiplexed with ISU1	functio	ons(SPI CLK/UART	TX)
15	GPIO33_MISO1_RXD1_SDA1	DIO	GPIO multiplexed with ISU1 functions(SPI MISO/UART RX/I2C DATA)			RX/I2C DATA)
16	GPIO35_CSB1	DIO	GPIO multiplexed with ISU1 functions(SPI CSB)			
17	RECOVERY_CTS	DI	Azure Sphere flash re-imaging Recovery UART CTS			Recovery UART is
18	RECOVERY_RTS	DO	Azure Sphere flash re-imaging Recovery UART RTS for upgrading the			for upgrading the
19	RECOVERY_TXD	DO	Azure Sphere flash re-imaging Recovery UART TXD  Azure Sphere OS without connection			without connection
20	RECOVERY_RXD	DI	Azure Sphere flash re-imagir	ng Rec	overy UART RXD	to the Internet.
21	SWO	DO	ARM SWO debug output	SWD	is used for program	ming and debugging
22	SWD_CLK	DI	ARM SWD clock	the 2	Cortex-M4 on MT3	3620.A single SWD
23	SWD_DIO	DIO	ARM SWD data	cnanr	nel is shared betwee	n two Cortex-M4.
24	DEBUG_RTS	DO	Azure Sphere OS debug RT /Strapping pin when MT3620 up		Debug UART is fo	r Microsoft use only.
25	DEBUG_TXD	DO	Azure Sphere OS debug TXI	D		
26	3V3	Р	DC 3.3V Power Supply		•	
27	GND	G	Ground			
28	3V3_RTC	Р	DC 3.3V for real-time clock			
29	EXT_PMU_EN	DO	Enable/disable external PML	J when	in deep sleep mode	e (RTC mode)
30	WAKEUP	DI	Wake from deep sleep (RTC	mode	)	
31	SYSRST_N	DI	System reset,active low.			
32	SERVICE_TXD	DO	Azure Sphere Service UART	TXD		he main interface for
33	SERVICE_RTS	DO	Azure Sphere Service UART RTS  PC to communicate with the Azure Sphere OS.Core A7 app debugging,			
34	SERVICE_RXD	DI	Azure Sphere Service UART RXD  Azure Sphere Service UART RXD  device ID operation all use the Service ID operation all use the Servi			turing test, getting
35	SERVICE_CTS	DI	Azure Sphere Service UART	CTS	UART port.	222 413 2314130
36	GND	G	Ground		•	
37	GND	G	Ground			

#### Note:

- 1.ISU is a serial communication block supporting I2C,SPI and UART interfaces.
- 2. The power supply for all GPIO pins is 3.3V.
- 3.The MT3620AN ADC VREF maximum is 2.5V.The module WF-M620-RSC1 has ADC VERF hooked up internally to 2.5V.Should not input >2.5V when using the ADC because the ADC will not read any value higher than 2.5V.If the ADC pin is not configured for ADC operation, then 3.3V input is ok.
- 4.In order to expose more pin functions of MT3620 on the small number of available module pins,two MT3620 pins share one module pin on module pin 1-8.At chip startup there should be no issue since all of these pins default to input. And please be careful when use these pins.

#### 2.3 Product Pictures





#### 3. RF Characteristics:

#### 3-1 IEEE 802.11b Section:

Items	Contents				
Specification		IEEE802.11b			
Mode			CCK		
Channel			CH1 to CH1	3	
Data rate		1,	2, 5.5, 11Mb	ps	
	Min.	Тур.	Max.	Unit	Remark
TX Characteristics					
Power Levels(Calibrated)					
1) for each data rate	14	16	18	dBm	
2. Spectrum Mask @ target power					
1) fc +/-11MHz to +/-22MHz	-	-	-30	dBr	
2) fc > +/-22MHz	-	-	-50	dBr	
3 Constellation Error(EVM)@ target power					
1) 1Mbps	-	-	-10	dB	
2) 2Mbps	-	-	-10	dB	
3) 5.5Mbps	-	-	-10	dB	
4) 11Mbps	-	-23	-10	dB	
4. Frequency Error	-10	-5	10	ppm	
RX Characteristics	Min.	Тур.	Max.	Unit	
5 Minimum Input Level Sensitivity(each chain)					
1) 1Mbps (FER ≤8%)	-	-98	-95	dBm	

2) 2Mbps (FER ≤8%)	-	-95	-93	dBm	
3) 5.5Mbps (FER ≤8%)	-	-93	-91	dBm	
4) 11Mbps (FER ≤8%)	-	-90	-88	dBm	
6 Maximum Input Level (FER ≤8%)	-10	-	-	dBm	

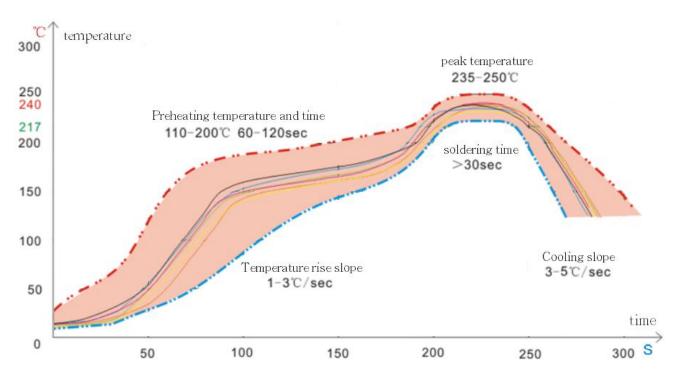
# 3-2 IEEE 802.11g Section:

Items	Contents				
Specification			EEE802.11	]	
Mode	OFDM				
Channel	CH1 to CH13				
Data rate		6, 9, 12, 1	8, 24, 36, 48	3, 54Mbps	
	Min.	Тур.	Max.	Unit	Remark
TX Characteristics					
1. Power Levels					
1) For Each data rate	13	15	17	dBm	
2. Spectrum Mask @ target power					
1) at fc +/-11MHz	-	-	-20	dBr	
2) at fc +/-20MHz	-	-	-28	dBr	
3) at fc > +/-30MHz	-	-	-40	dBr	
3 Constellation Error(EVM)@ target power					
1) 6Mbps	-	-	-5	dB	
2) 9Mbps	-	-	-8	dB	
3) 12Mbps	-	-	-10	dB	
4) 18Mbps	-	-	-13	dB	
5) 24Mbps	-	-	-16	dB	
6) 36Mbps	-	-	-19	dB	
7) 48Mbps	-	-	-22	dB	
8) 54Mbps	-	-37	-25	dB	
4 Frequency Error	-10	-5	10	ppm	
RX Characteristics	Min.	Тур.	Max.	Unit	
5 Minimum Input Level Sensitivity(each chain)					
1) 6Mbps (PER ≤10%)	-	-95	-92	dBm	
2) 9Mbps (PER ≤ 10%)	-	-92	-90	dBm	
3) 12Mbps (PER ≤ 10%)	-	-90	-88	dBm	
4) 18Mbps (PER ≤10%)	-	-88	-86	dBm	
5) 24Mbps (PER ≤ 10%)	-	-85	-83	dBm	
6) 36Mbps (PER ≤ 10%)	-	-83	-81	dBm	
7) 48Mbps (PER ≤ 10%)	-	-78	-76	dBm	
8) 54Mbps (PER ≤ 10%)	-	-76	-74	dBm	
6 Maximum Input Level (PER ≤ 10%)	-20	-	-	dBm	

## 3-3 IEEE 802.11n HT20 Section:

Items	Contents				
Specification		IEEE802.11n HT20 @ 2.4GHz			
Mode		OFDM			
Channel		(	CH1 to CH1	3	
Data rate (MCS index)		MC	S0/1/2/3/4/5	/6/7	
TX Characteristics	Min.	Тур.	Max.	Unit	Remark
2. Power Levels					
1) For Each antenna port	12	14	16	dBm	
3. Spectrum Mask @target power					
1) at fc +/-11MHz	-	-	-20	dBr	
2) at fc +/-20MHz	-	-	-28	dBr	
3) at fc > +/-30MHz	-	-	-45	dBr	
4. Constellation Error(EVM)@ target power					
1) MCS0	-	-	-5	dB	
2) MCS1	-	-	-10	dB	
3) MCS2	-	-	-13	dB	
4) MCS3	-	-	-16	dB	
5) MCS4	-	-	-19	dB	
6) MCS5	-	-	-22	dB	
7) MCS6	-	-	-25	dB	
8) MCS7	-	-37	-28	dB	
5. Frequency Error	-10	-	10	ppm	
RX Characteristics	Min.	Тур.	Max.	Unit	
6. Minimum Input Level Sensitivity(each chain)					
1) MCS0 (PER ≤ 10%)	-	-94	-90	dBm	
2) MCS1 (PER ≤ 10%)	-	-90	-88	dBm	
3) MCS2 (PER ≤ 10%)	-	-87	-85	dBm	
4) MCS3 (PER ≤ 10%)	-	-85	-83	dBm	
5) MCS4 (PER ≤ 10%)	-	-82	-80	dBm	
6) MCS5 (PER ≤ 10%)	-	-77	-75	dBm	
7) MCS6 (PER ≤ 10%)	-	-75	-73	dBm	
8) MCS7 (PER ≤ 10%)	-	-75	-73	dBm	
7. Maximum Input Level (PER ≤10%)	-20	-	-	dBm	

### 4. Refelow Standard Condition



## 5. Key Materials

Item	Category	MPN	Description	MFR	Notes
1	IC	MT3620AN	165-QFN	MTK	
2	PCB	JUI7.820.0392-5	FR-4,4LAY	Sunlord IQPCB SHPCB	
3	Crystal Oscillator	-	26MHz,2520,11pF± 10ppm,-20~75°C; 32.768KHZ,2012,11p F±20ppm,-40~85°C;	JWT Hosonic TXC	

### 6. Package

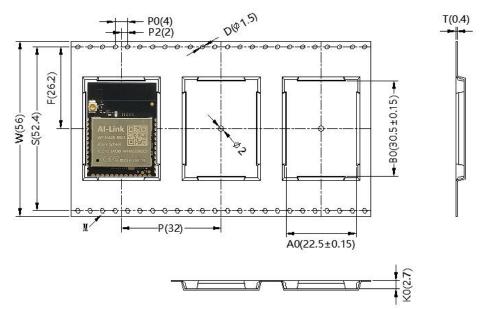


Figure 13.1 Dimensions of Tape









Figure 13.2 Packaging Details

#### Notes:

1.Dimensions of the inner box:355mm\*355mm\*72mm;

Dimensions of the Outer case:370mm\*370mm\*300mm;

2.600PCS modules per tape,1 tape for each inner box,4 inner boxes for each outer case,and total 2400PCS modules per outer case;